

What is claimed is:

1. A porous insulating film comprising a highly heat resistant resin film having a fine porous structure with a mean pore size of 0.01-5 μm in at least the center of the film, and having a porosity of 15-80%. 5
2. A porous insulating film according to claim 1, wherein the mean pore size is 0.05-1 μm .
3. A porous insulating film according to claim 1, wherein the porosity is 30-80%.
- 10 4. A porous insulating film according to claim 1, which has a thickness of 5-150 μm .
5. A porous insulating film according to claim 1, wherein the fine porous structure consists of fine continuous pores.
- 15 6. A porous insulating film according to claim 1, which is fabricated by a film casting method.
7. A porous insulating film according to claim 1, wherein the dielectric constant is no greater than 2.5.
8. A porous insulating film according to claim 1, 20 wherein the highly heat resistant resin film is a polyimide film.
9. A porous insulating film according to claim 1, wherein the porous structure has fine continuous pores reaching to both surfaces.
- 25 10. A porous insulating film according to claim 9, which has a porosity of 30-80%, a maximum pore size of no greater than 10 μm , a film thickness of 5-100 μm , a resistance to passage of air of from 30 sec/100 cc to 2000 sec/100 cc, a heat resistance temperature of 200°C or above and a heat shrinkage of no greater than $\pm 1\%$.
- 30 11. A porous insulating film according to claim 1, wherein the porous structure has a dense layer on both surfaces of the film.
- 35 12. A laminate prepared by forming a heat resistant adhesive layer on one or both sides of a porous insulating film according to claim 1.

13. A laminate prepared by laminating a conductive metal layer for an electronic circuit on one or both sides of a porous insulating film according to claim 1, either directly or via a heat resistant adhesive layer.

5 14. A laminate prepared by laminating an inorganic or metal substrate onto one side of a porous insulating film according to claim 1 and a conductive metal layer onto the other side, each via a heat resistant adhesive layer.